Tool Make & Model

Solitec: 5100-C

Tool Configuration / Specifications

APPLICATIONS:
-Positive resist coatings on wafers, masks and substrates
-Negative resist coating on wafers, masks and substrates
-PMMA and E-Beam resist coating
-Silicon, GaAs, InP and other semiconductor materials
-Polyimide coatings on wafers, masks and substrates
-Photosensitive polyimide coating
-Multi-layer resists

FEATURES:
-Single chuck for wafers, masks or substrates
-Solitec proprietary diaphragm type dispense pump
-100A, 3 sigma, full radius uniformity across a wafer
-Selectable process functions
-Downflow exhaust system for backsplash control
-N2 motor purge and interlock
-Vacuum interlock on wafer chuck
-Optional auto solvent dispense for HMDS
-5 gallon drain bucket with exhaust
-Closed loop servo speed control for tight process control
-1,000 to 40,000 rpm/sec acceleration
-High uptime, easy maintenance design
-Polypropelene waste container
-Digital tachometer with direct optical encoder
-t 10 rpm spin speed control
-Solvent dispense before coating (optional)
--N2 blow-off (optional)
-One wafer chuck and loading paddle included

The information contained in this data sheet is, to our knowledge, accurate. We do not warrant the completeness or accuracy of the information contained herein. Any offer by you to purchase the equipment described in this data sheet shall be subject to the terms and conditions of sale.